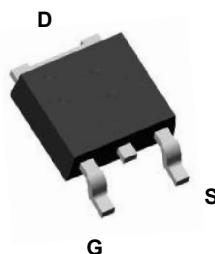
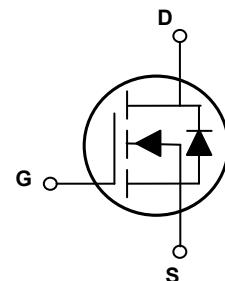


### Main Product Characteristics

$V_{(BR)DSS}$	800V
$R_{DS(ON)}$	0.90Ω (max.)
$I_D$	6A



TO-252 (DPAK)



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFD80R900 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	800	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous, at Steady-State, ( $T_C=25^\circ\text{C}$ )	$I_D$	6	A
Drain Current-Continuous, at Steady-State, ( $T_C=100^\circ\text{C}$ )		3.8	
Drain Current-Pulsed	$I_{DM}$	24	A
Single Pulse Avalanche Energy <sup>1</sup>	$E_{AS}$	214	mJ
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	66	W
Power Dissipation – Derate above 25°C		0.53	W/°C
Body Diode Reverse Voltage Slope <sup>2</sup>	$dv/dt$	50	V/ns
MOS $dv/dt$ Ruggedness <sup>3</sup>	$dv/dt$	100	V/ns
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.9	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	800	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=800\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3\text{A}$	-	0.75	0.90	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	-	4.0	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>4,5</sup>	$Q_g$	$V_{\text{DD}}=640\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$	-	17	-	nC
Gate-Source Charge <sup>4,5</sup>	$Q_{\text{gs}}$		-	5.0	-	
Gate-Drain ("Miller") Charge <sup>4,5</sup>	$Q_{\text{gd}}$		-	7.6	-	
Turn-On Delay Time <sup>4,5</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=400\text{V}, R_{\text{G}}=25\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$	-	14	-	nS
Rise Time <sup>4,5</sup>	$t_r$		-	34	-	
Turn-Off Delay Time <sup>4,5</sup>	$t_{\text{d}(\text{off})}$		-	44	-	
Fall Time <sup>4,5</sup>	$t_f$		-	26	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	568	-	pF
Output Capacitance	$C_{\text{oss}}$		-	22	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	0.95	-	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	7.6	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_s$	$T_c=25^\circ\text{C}$ , MOSFET symbol showing the integral reverse p-n junction diode.	-	-	6	A
Source Pulse Current	$I_{\text{SM}}$	-	-	24	A	
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_s=6\text{A}$	-	1.1	1.4	V
Reverse Recovery Time <sup>2</sup>	$t_{\text{rr}}$	$V_{\text{DD}}=50\text{V}, I_F=6\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	348	-	nS
Reverse Recovery Charge <sup>2</sup>	$Q_{\text{rr}}$		-	2.7	-	uC

Note:

1.  $L=79\text{mH}, I_{\text{AS}}=2.2\text{A}, V_{\text{DD}}=100\text{V}, R_g=25\Omega$ , starting temperature  $T_j=25^\circ\text{C}$ .
2.  $V_{\text{DS}}=0 \text{ - } 400\text{V}, I_{\text{SD}} \leq I_s, T_j=25^\circ\text{C}$ .
3.  $V_{\text{DS}}=0 \text{ - } 480\text{V}$ .
4. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
5. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

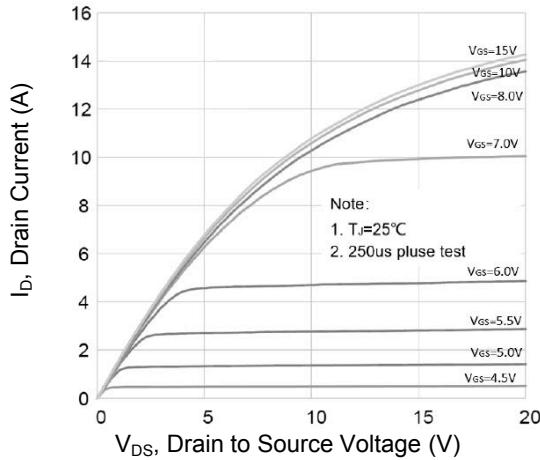


Figure 1. Typical Output Characteristics

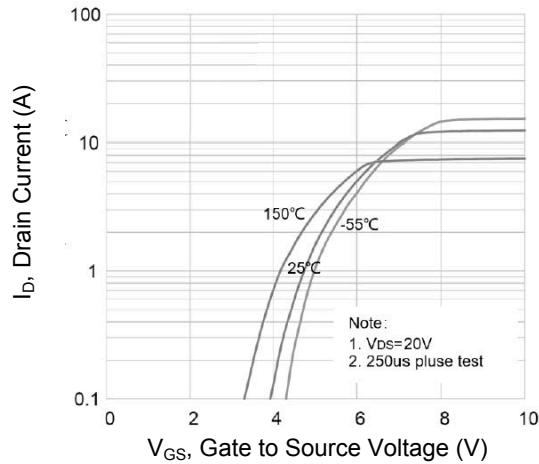


Figure 2. Typical Transfer Characteristics

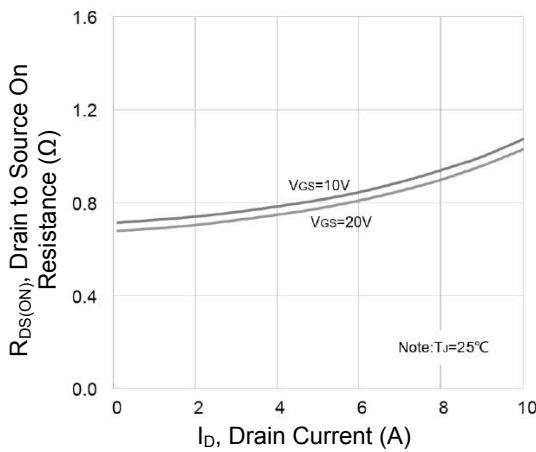


Figure 3.  $R_{DS(ON)}$  vs. Drain Current

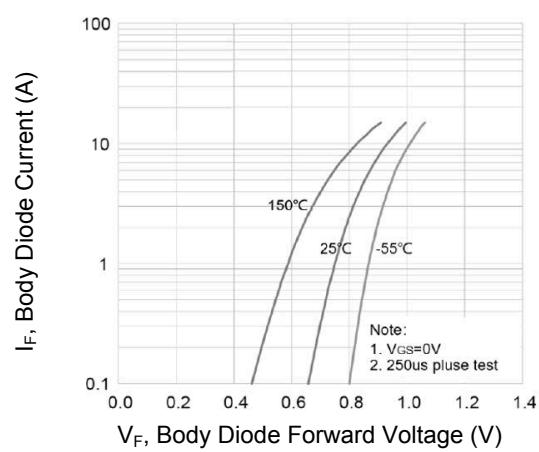


Figure 4. Body Diode Characteristics

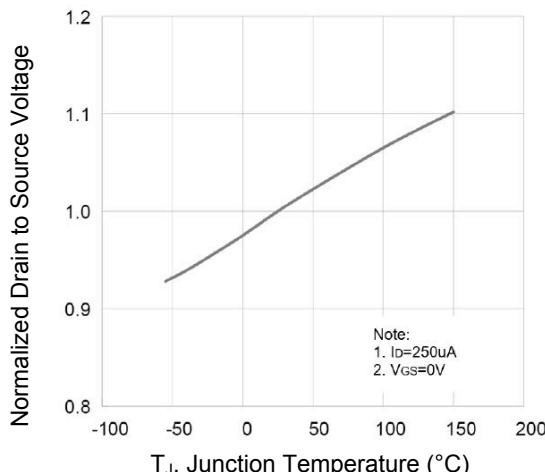


Figure 5. Normalized  $BV_{DSS}$  vs. Junction Temperature

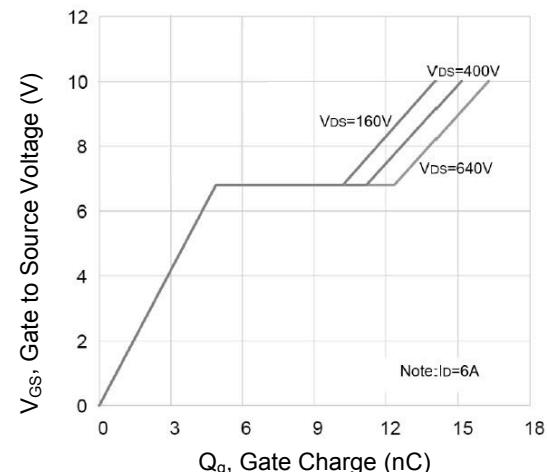


Figure 6. Gate Charge Characteristics

## Typical Electrical and Thermal Characteristic Curves

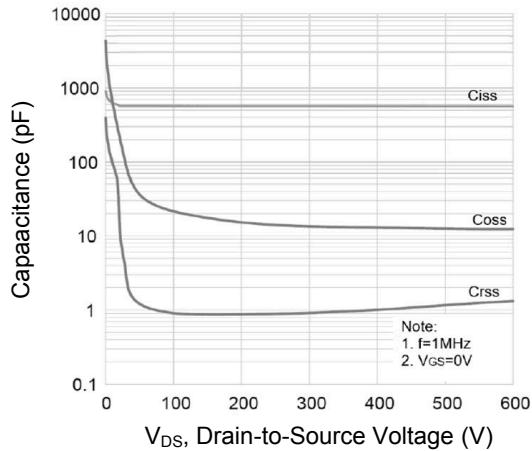


Figure 7. Capacitance Characteristics

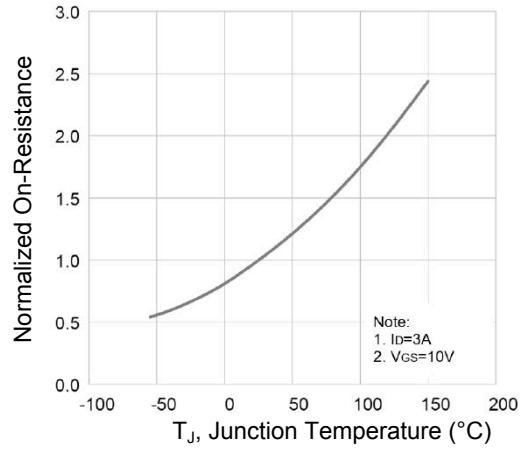


Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$

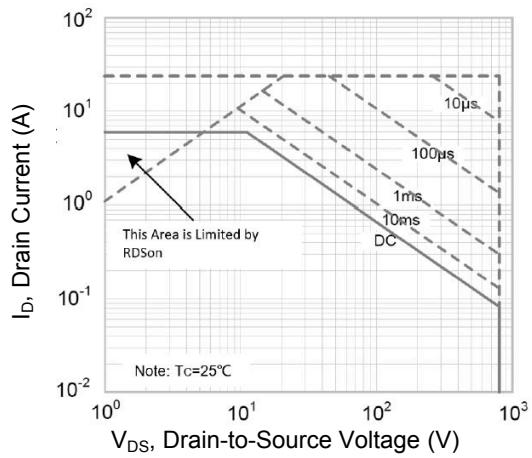
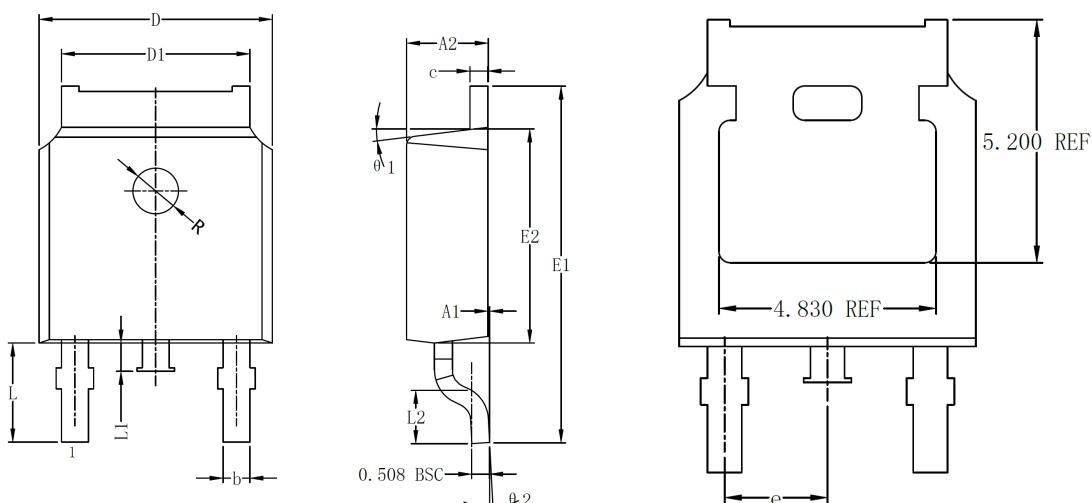


Figure 9. Safe Operation Area

**Package Outline Dimensions TO-252 (DPAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.127	0.000	0.005
A2	2.200	2.400	0.087	0.094
b	0.660	0.860	0.026	0.034
c	0.508 REF		0.020 REF	
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
e	2.286 BSC		0.090 BSC	
E1	9.700	10.100	0.382	0.398
E2	6.000	6.200	0.236	0.244
L	2.850 REF		0.112 REF	
L1	0.600	1.000	0.024	0.039
L2	1.400	1.700	0.055	0.067
R	1.300 REF		0.051 REF	
θ1	7° REF		7° REF	
θ2	0°	10°	0°	10°